

REMARKS

Favorable reconsideration of this application is requested. A typographical revision is made to claim 1 above. Claims 1-2 remain actively pending in the case. No new matter has been added. Reconsideration of the claims are respectfully requested.

35 USC § 102 Rejections

Claims 1 and 2 were rejected as anticipated under §102(b) by Mori et al. (JP 4-94732). Applicant traverses this rejection. Mori fails to disclose or suggest that an area of each of said facedown bonding dummy bumps projected onto a chip is larger than that of the area of each said facedown bonding bumps, the height of the facedown bonding dummy bumps being the same as the height of the facedown bonding bumps (i.e., as recited in Applicant's claim 1). Rather, Mori discloses that the dummy bumps 23 in at least Figs. 1 and 2 have the same area as that of bumps 22. Furthermore, the dummy bumps in at least Figs. 3-10 have different heights than connection bumps. Therefore, in view of the above remarks, Applicant's independent claim 1 is patentable over the cited reference.

Claims 1 and 2 were rejected as anticipated under §102(e) by Nishikawa (US 2003/0092326). Applicant traverses this rejection. Nishikawa fails to disclose or suggest that an area of each of said facedown bonding dummy bumps projected onto a chip is larger than that of the area of each said facedown bonding bumps, the height of the facedown bonding dummy bumps being the same as the height of the facedown bonding bumps (i.e., as recited in Applicant's claim 1). Rather, Nishikawa discloses dummy bumps 23 that are the same area as the normal bumps 22. Furthermore, in Nishikawa, the purpose of the dummy bump is to regulate the flow of a bonding material 25, which is different than the present invention. Therefore, in view of the above remarks, Applicant's independent claim 1 is patentable over the cited reference.

Claims 1 and 2 were rejected as anticipated under §102(e) by Kimura (US 2003/0060035). Applicant traverses this rejection. Kimura also fails to disclose or suggest that an area of each of said facedown bonding dummy bumps projected onto a chip is larger than that of the area of each said facedown bonding bumps, the height of the facedown bonding dummy bumps being the same as the height of the facedown bonding bumps (i.e., as recited in

Applicant's claim 1). Rather, Kimura discloses that dummy bumps 3 have the same area as function bumps 2. Therefore, in view of the above remarks, Applicant's independent claim 1 is patentable over the cited reference.

Claims 1 and 2 were rejected as anticipated under §102(e) by JP 2003-282812. Applicant traverses this rejection. The rejection is made under 35 USC 102(e). However, §102(e) applies only to US patents or published applications. More specifically, §102(e) states:

. . . the invention was described in – (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent,

Since the reference cited by the Examiner is a Japanese document, it was not filed in the United States as specifically required under §102(e). Therefore, the rejection is incorrect. Further, the reference does not operate as a §102(a) reference since its publication date is October 3, 2003, which is after the October 31, 2002 priority date of the present application. In view of the foregoing, this rejection should be withdrawn. If the Examiner maintains this rejection, the Applicant respectfully requests that the Examiner specifically describe how §102(e) is being used in connection with the Japanese reference.

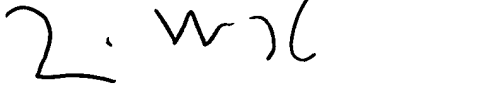
In view of the above remarks, Applicant's independent claim 1 is patentable over the cited references. Because claim 2 depends from claim 1, and includes the features recited in the independent claim, the Applicant respectfully submits that claim 2 is also patentably distinct over the cited reference. Nevertheless, Applicant is not conceding the correctness of the Office Action's rejection with respect to such dependent claim and reserves the right to make additional arguments if necessary.

Favorable reconsideration in the form of a Notice of Allowance is requested.

Respectfully Submitted,

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